

Part Number: <u>1700714013</u>

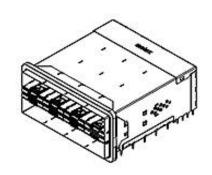
Product Description : zSFP+ Stacked Ganged Assembly with Elastomeric Gasket, 2-by-4 with Outer

Down/Up Light Pipes, 160 Circuits

Series Number: 170071

Status: Active

Product Category: High-Speed I/O Connectors



Documents & Resources

Drawings

1700714013 sd.pdf

3D Models and Design Files

STEP AP242

SOLIDWORKS

Creo

SYM-170071-0001-001.zip

EE-170071-0001-001.pdf

SP-170426-1000-001.zip

Specifications

AS-170071-0002-001.pdf

PS-170071-0001-001.pdf

TS-170071-0001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34;
	33
China RoHS	⊚
Crima Norts	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC

	(25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	170071
Description	zSFP+ Stacked Ganged Assembly with Elastomeric Gasket, 2-by-4 with Outer Down/Up Light Pipes, 160 Circuits
Application	Module-to-Board
Component Type	Receptacle
Product Name	zSFP Plus,zSFP+
Туре	Pluggable
UPC	884982402218

Agency

UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Data Rate	28.0 Gbps
Shielded	Yes
Shield Type	N/A
Voltage - Maximum	30V AC

Physical

Circuits (Loaded)	160
Color - Resin	Black
Durability (mating cycles max)	100
Flammability	94V-0
Gender	Female
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	96.132/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.36mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	8
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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Application Tooling

This document was generated on Aug 03, 2025